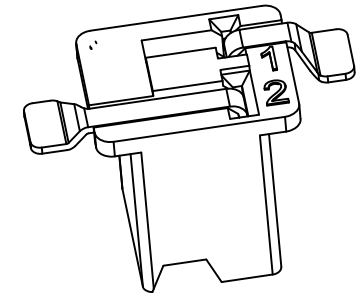
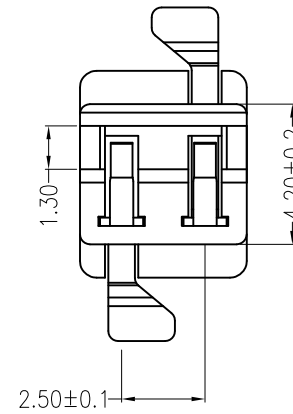
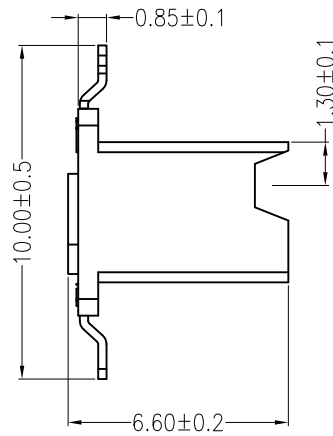
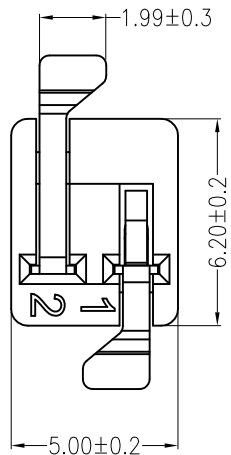


REV	DESCRIPTION	DESIGN	DATE
A0	Release	吴丹平	2016.04.30
A1	Add circuit board diagram	Jiangjianyin	2020.07.25

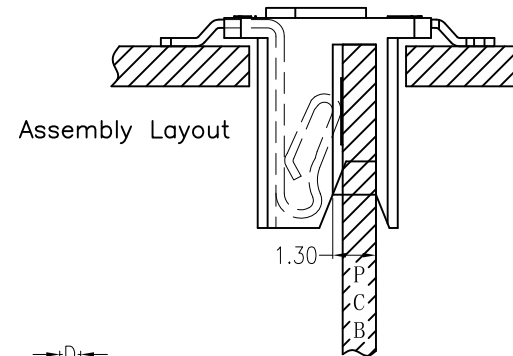


主要技术参数 Main Specifications

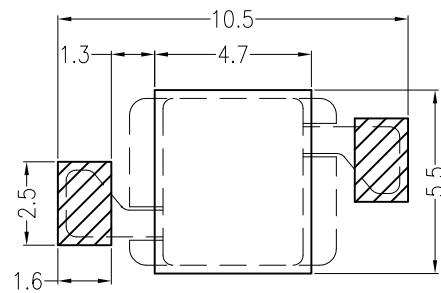
板 厚 (thickness): 1.0mm to 1.2mm
接触电阻 (Contact resistance): $\leq 20\text{m}\Omega$
绝缘电阻 (Insulation resistance): $\geq 1000\text{M}\Omega$
额定电压 (Rated voltage): 250V AC DC
额定电流 (Rated current): 1.0A AC DC
耐 电 压 (Withstand Voltage): 1000V AC/minute
温度范围 (Temperature Range): $-40^{\circ}\text{C} \sim +120^{\circ}\text{C}$

ORDER INFORMATION:

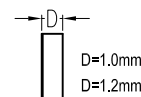
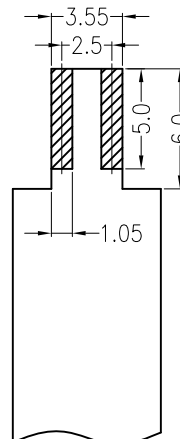
L047-02-F2MB-R			
PART No.		PACKAGING:	
No. FOR CIRCUITS:		R=REEL	
02		P=PE	
PLASTIC MATERIAL:		PLATING:	
F2M=LCP (BEIGE)		B=MATTE Sn	



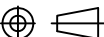
Assembly Layout



Board Layout



Circuit board

C					
B	CONTACT		2 PCS	PhosphorBronze	MATTE Sn-plated
A	PEDESTAL		1 PCS	LCP	UL 94V-0, COLOR:BEIGE
ITEM	COMPONENT		Q'TY	MATERIAL	FINISH
 东莞市高迪电子有限公司 DONG GUAN GAO DI ELECTRONICS CO., LTD				TITLE: - 2.5mmPITCH 180°WAFER SMT TYPE	
X.±0.5		X.±5°	USE: CUSTOMER APPD: 王锋 CHKD: 曾令青	PART NO.: L047-02-F2MB-R	
.X±0.3		.X±2°		DWG NO.: GCCP-0076	
.XX±0.25		.XX±1°		SCALE 1 : 1	
--		--		SHEET 1 / 1	
		UNITS: mm	DR: 蒋建银		